

CATALOG NUMBER

R008-L95-01-T

MATERIAL AND FINISH

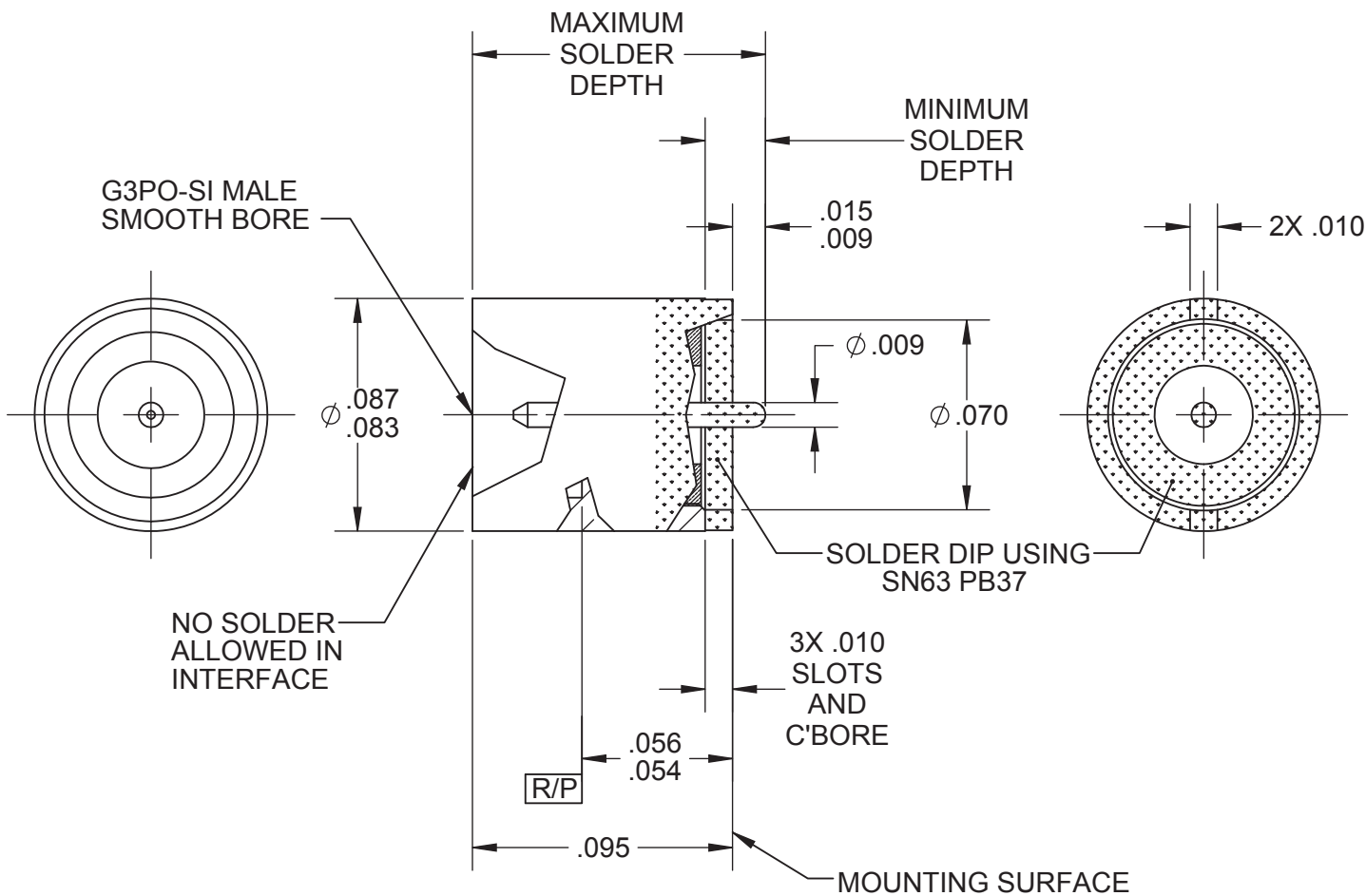
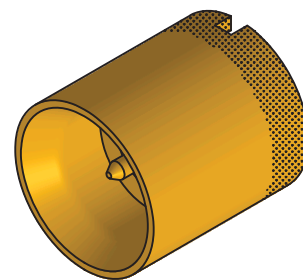
HOUSING, BUSHING,
AND CENTER CONTACT:

BeCu; GOLD PLATE 75 MICROINCHES TYPICAL
OVER COPPER FLASH



DIELECTRICS:

POLYAMIDE-IMIDE



NOTES:

1. NON-MAGNETIC PLATING. THIS CONNECTOR IS NOT TO BE USED IN STANDARD APPLICATIONS.
2. ALL DIMENSIONS APPLY BEFORE SOLDER DIP.

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APPROX. WEIGHT:	0.0423 grams	SIGNATURES	INIT	DATE:
TOLERANCE:		DRAWN:	DMG	6/2/16
.XX ±.010 .XXX ±.005 ANGULAR ±5°		CHECKED:	BLK	
		APPROVED:	TEF	

G3PO-SI MALE SMOOTH BORE PCB MOUNT (NON-MAGNETIC, SOLDER DIPPED)	CAGE CODE: 82316	SCALE: 15:1		PLANT OF ORIGIN
	REVISION: 02			CORNING PHOENIX PLANT: (623)245-1050 CUSTOMER SERVICE: (800) 651-8869

SOURCE FILE:	SK-4366	DWG. NO.:	OL-R008-L95-01-T	ASSY. PROC.:	-
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